

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

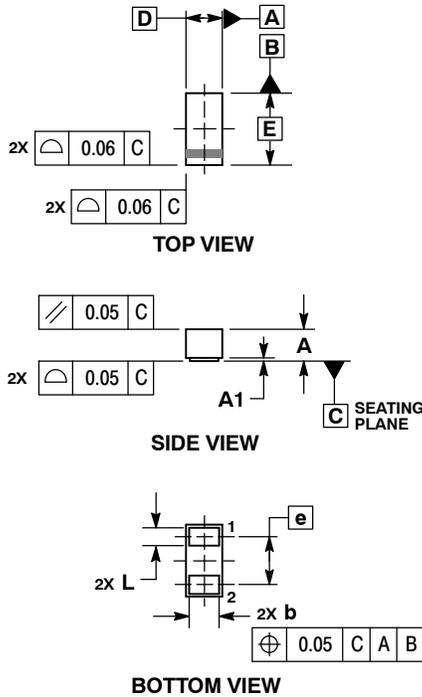


2 Pin Flip-Chip, 0.6x0.3

CASE 499BA-01
ISSUE O


SCALE 8:1

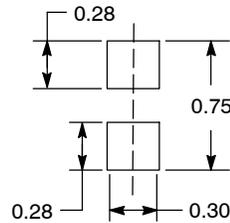
DATE 08 JUL 2008



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.

MILLIMETERS		
DIM	MIN	MAX
A	0.24	0.30
A1	0.00	0.05
b	0.22	0.28
D	0.30	BSC
E	0.60	BSC
e	0.40	BSC
L	0.12	0.18

MOUNTING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	2 PIN FLIP-CHIP, 0.6X0.3	PAGE 1 OF 2

